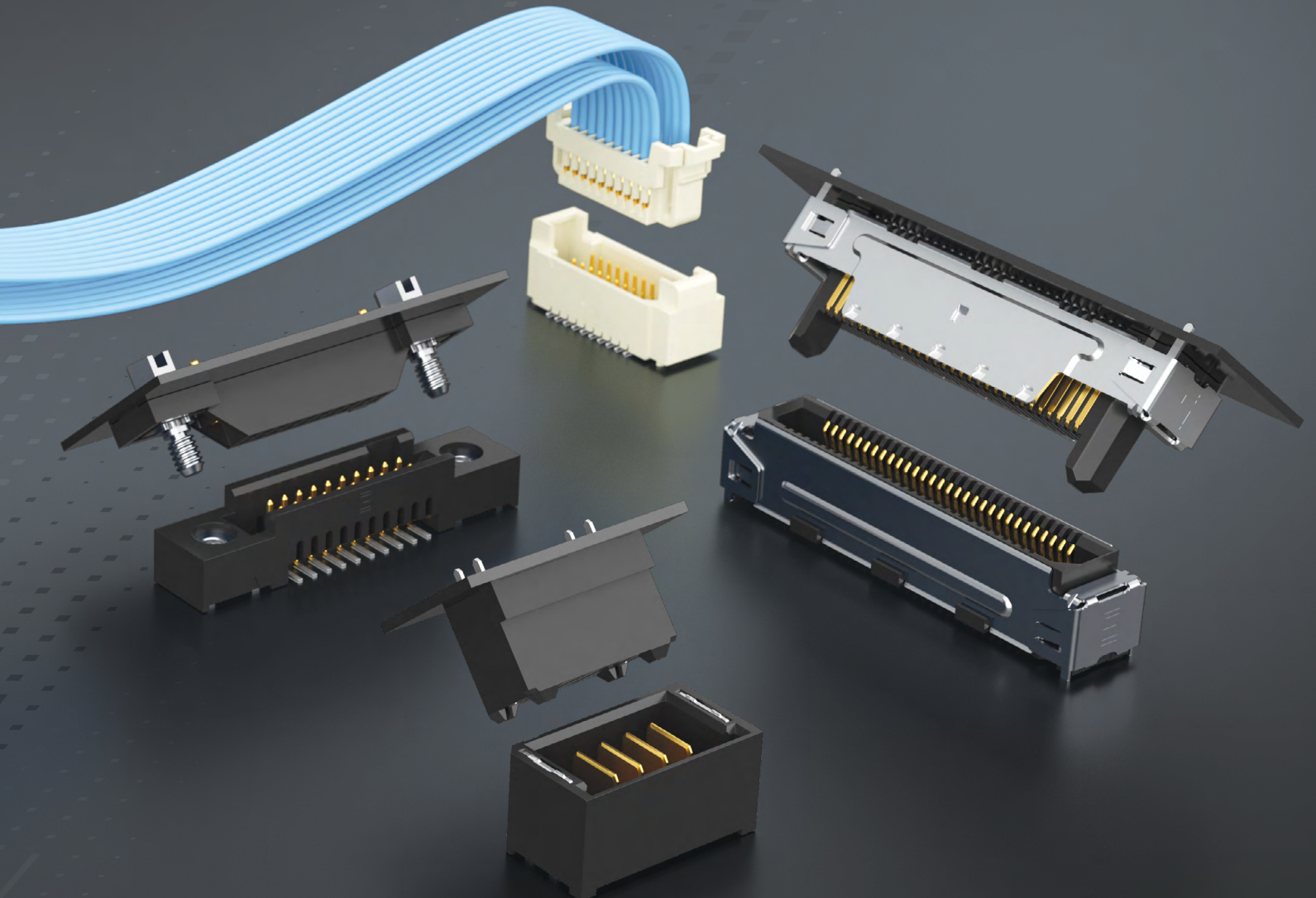




MICRO RUGGED

APPLICATION DESIGN GUIDE



MICRO RUGGED

INTERCONNECT SOLUTIONS

Rugged contact systems, micro power interconnects and rugged signal integrity create the foundation of Samtec's micro rugged solutions for high cycle, high power and harsh environment applications. Samtec's rugged products are offered in conjunction with full engineering support, online tools and a service attitude that is unmatched in the connector industry.

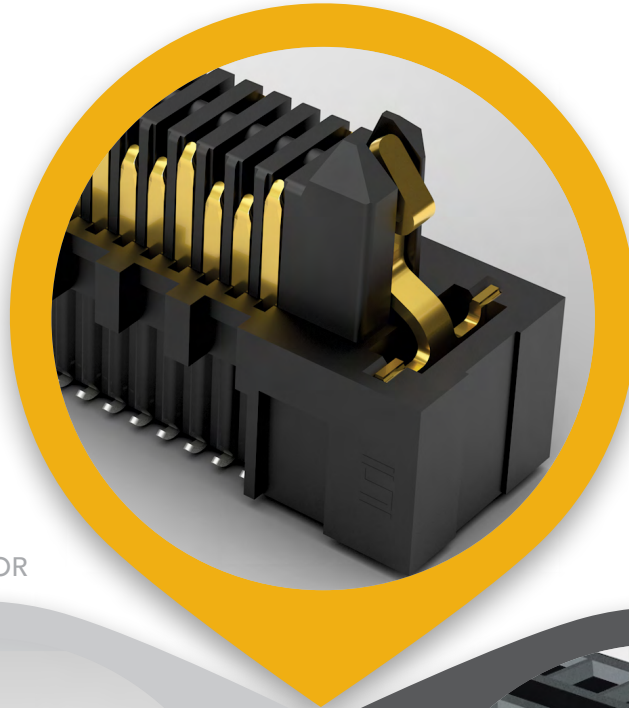
MP

MICRO POWER

3 TO 30 AMPS

CONFIGURABILITY OF
POWER & SIGNAL

SPACE-SAVING FORM FACTOR



SI

RUGGED SIGNAL INTEGRITY

HIGH SPEEDS TO 40 Gbps

EDGE RATE® CONTACT DESIGN
INCREASES WEAR LIFE

EXPERTISE IN SIGNAL
INTEGRITY DESIGN & ANALYSIS



R

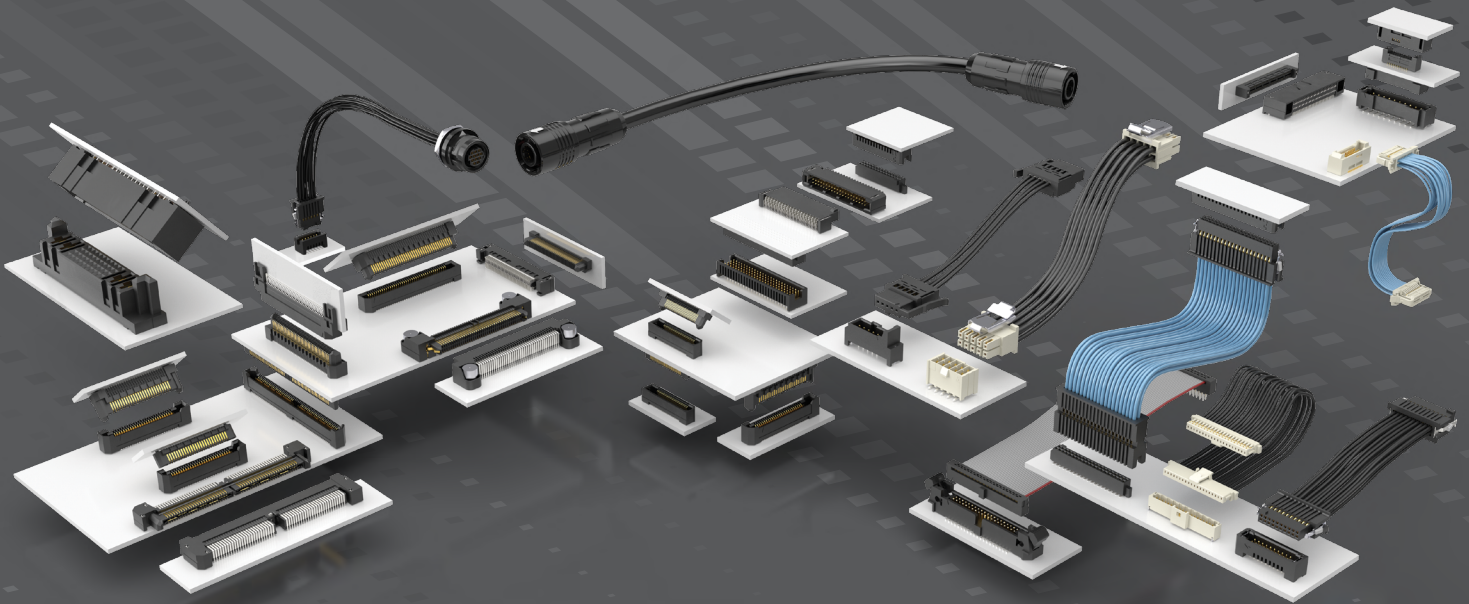
RUGGED CONTACT SYSTEM

1,000+ MATING CYCLES

TIGER EYE™ HEAT-TREATED BeCu CONTACTS

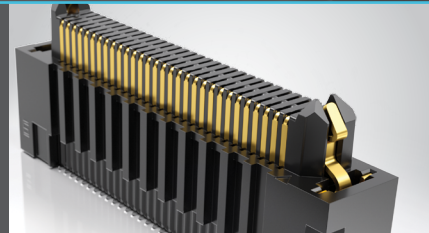
REDUNDANT POINTS OF CONTACT FOR HIGH-RELIABILITY

Learn more at
www.samtec.com



BOARD-TO-BOARD SYSTEMS

- Edge Rate® system for rugged signal integrity performance
- Tiger Eye™ contact system for high-reliability in rugged applications
- 0.50 mm to 2.00 mm pitch
- Stack heights from 5 mm to 18 mm



4-9

MICRO POWER SYSTEMS

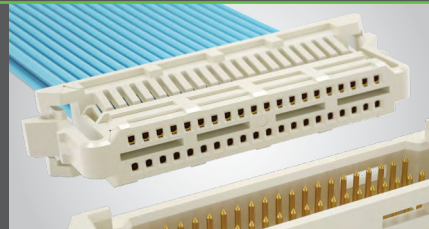
- 3 to 30 A per power blade
- Small form factor
- Micro power/signal combinations
- Variety of pitches



10-11

DISCRETE WIRE ASSEMBLIES

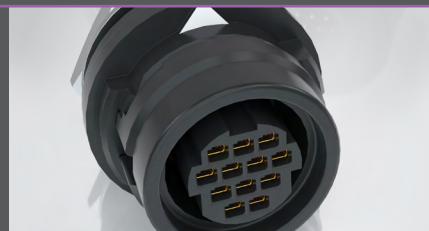
- Choice of pitch as low as 0.80 mm
- Rugged, high-performance Tiger Eye™ systems
- Individually shrouded contacts
- High power systems to 34.5 A per power blade



12-13

SEALED I/O SYSTEMS

- IP68 and IP67 rated for dust and water
- Variety of circular shell sizes with power, power/signal pin outs
- Rectangular designs for space savings
- Rugged latching



14

Modified & Custom Solutions

15

Solutionator®

16

Rugged Features

17

Power Integrity & Extended Life Product™

18

Full System Signal Integrity

19

SI R MP

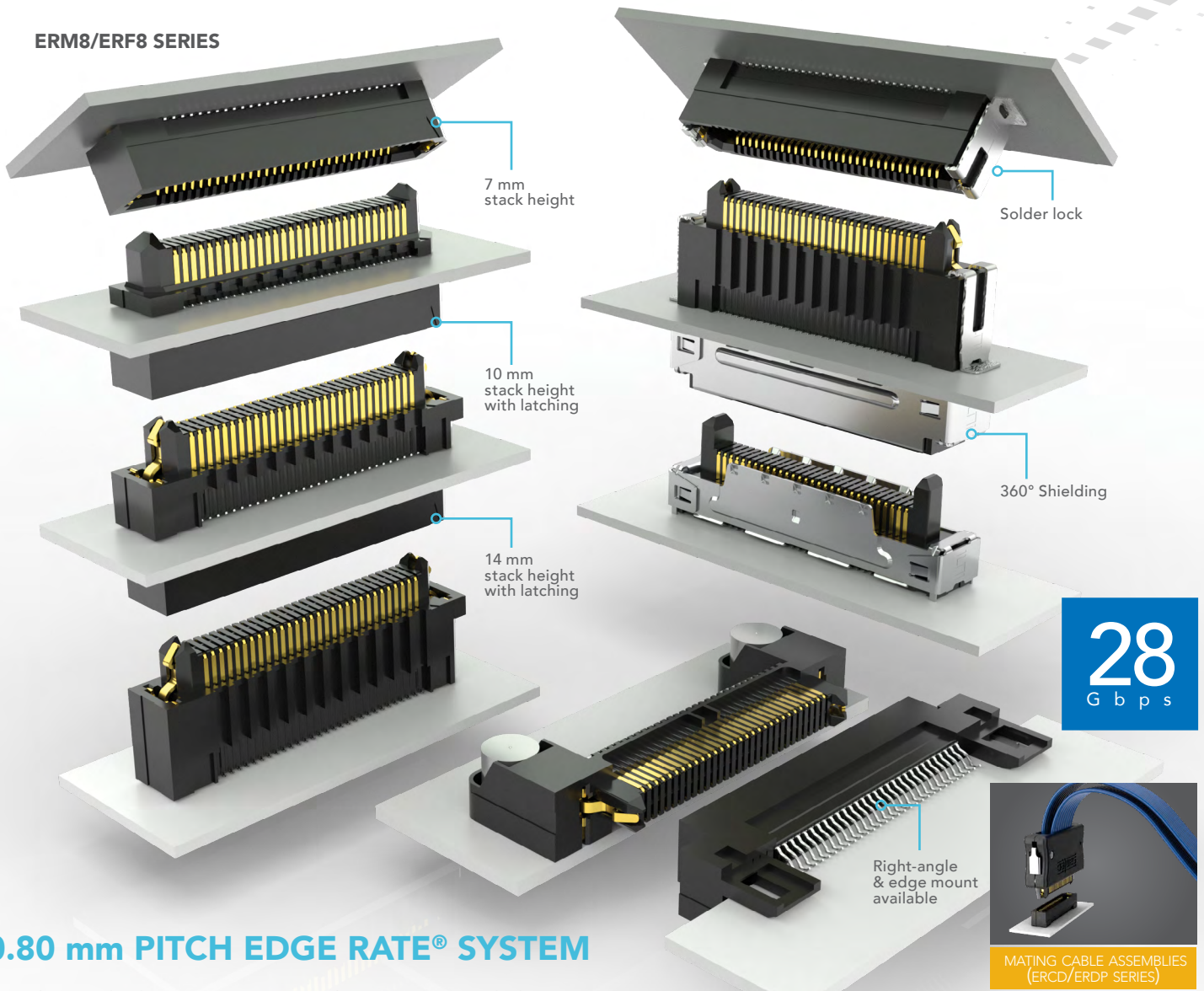
EDGE RATE CONTACT



EDGE RATE® CONTACT SYSTEMS

OPTIMIZED FOR SI PERFORMANCE • INCREASED CONTACT WIPE • HIGH CYCLES

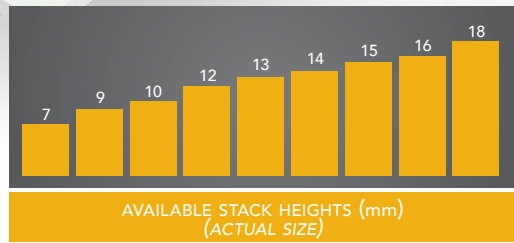
ERM8/ERF8 SERIES



28 Gbps

0.80 mm PITCH EDGE RATE® SYSTEM

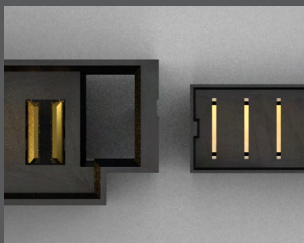
- High-speed Edge Rate® contacts with 1.50 mm extended wipe
- Rugged metal latching for increased retention force
- 360° shielding option reduces EMI
- Cost-effective metal solder lock in development for a more secure connection to the board



? Samtec designs and builds all automation equipment in-house.

MICRO POWER SYSTEM

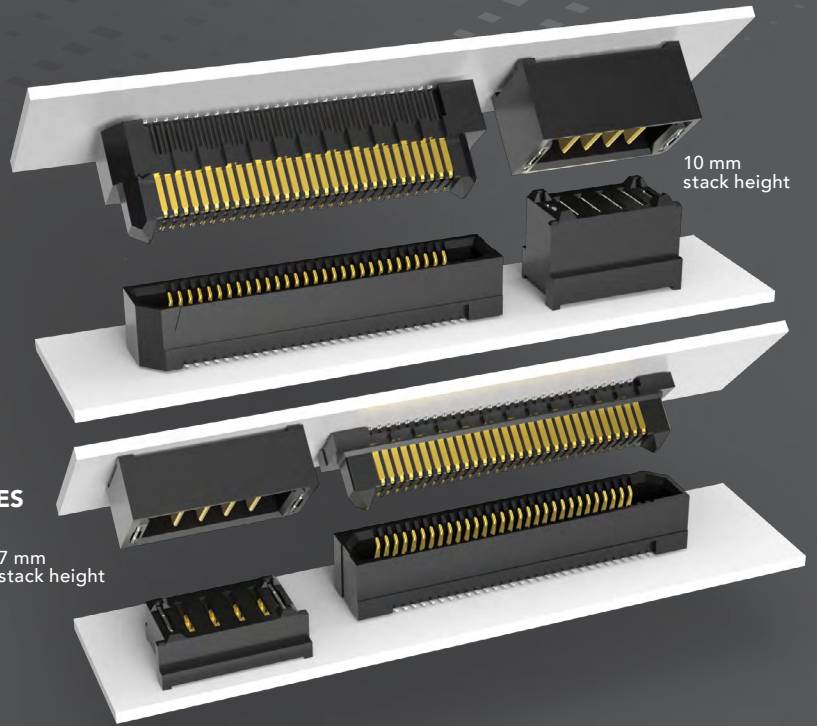
- Use with Samtec's Edge Rate® and other high-speed systems for power/signal applications
- 5 mm to 20 mm stack heights
- 2 to 5 power blades on a 2.00 mm pitch
- Allows for staging of power and signal/ground
- Modular interlocking, shielding and right-angle options in development



2.00 mm PITCH VS.
3.81 mm PITCH (UPX SERIES)

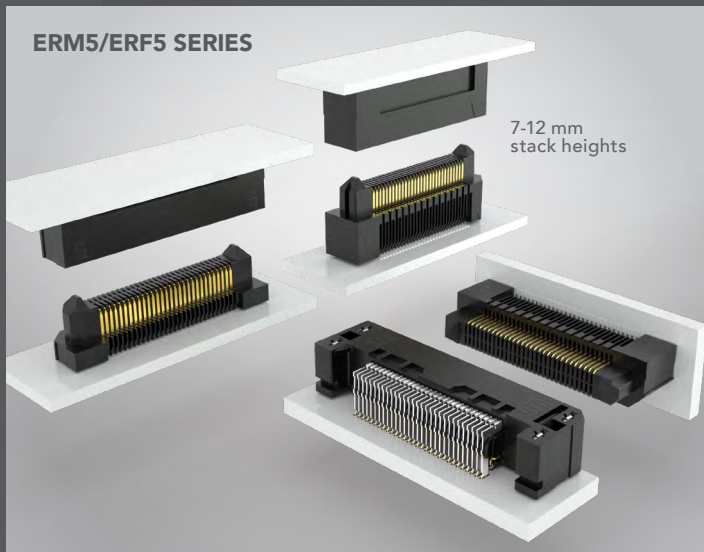
UMPT/UMPS SERIES

15 A
per power pin
4 pins powered



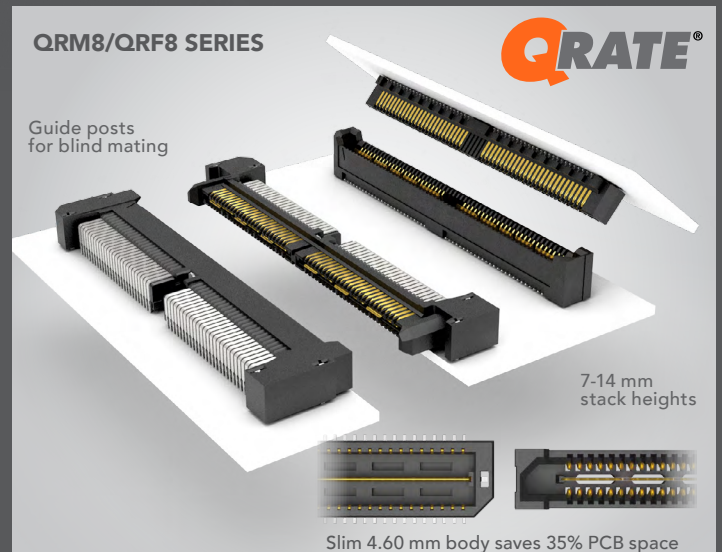
0.50 mm PITCH EDGE RATE®

- 1.00 mm contact wipe for a reliable connection
- 28 Gbps high-speed channel performance*
- Rugged friction locks and weld tabs available
- Up to 40% PCB space savings vs. ERM8/ERF8



Q RATE® SLIM GROUND PLANE

- Widely accepted industry standard integral power/ground plane
- 0.80 mm pitch with 1.20 mm contact wipe
- 31 Gbps high-speed channel performance*



* High-speed channel performance figure based on Samtec reference channel. For full SI Performance data visit samtec.com or contact sig@samtec.com

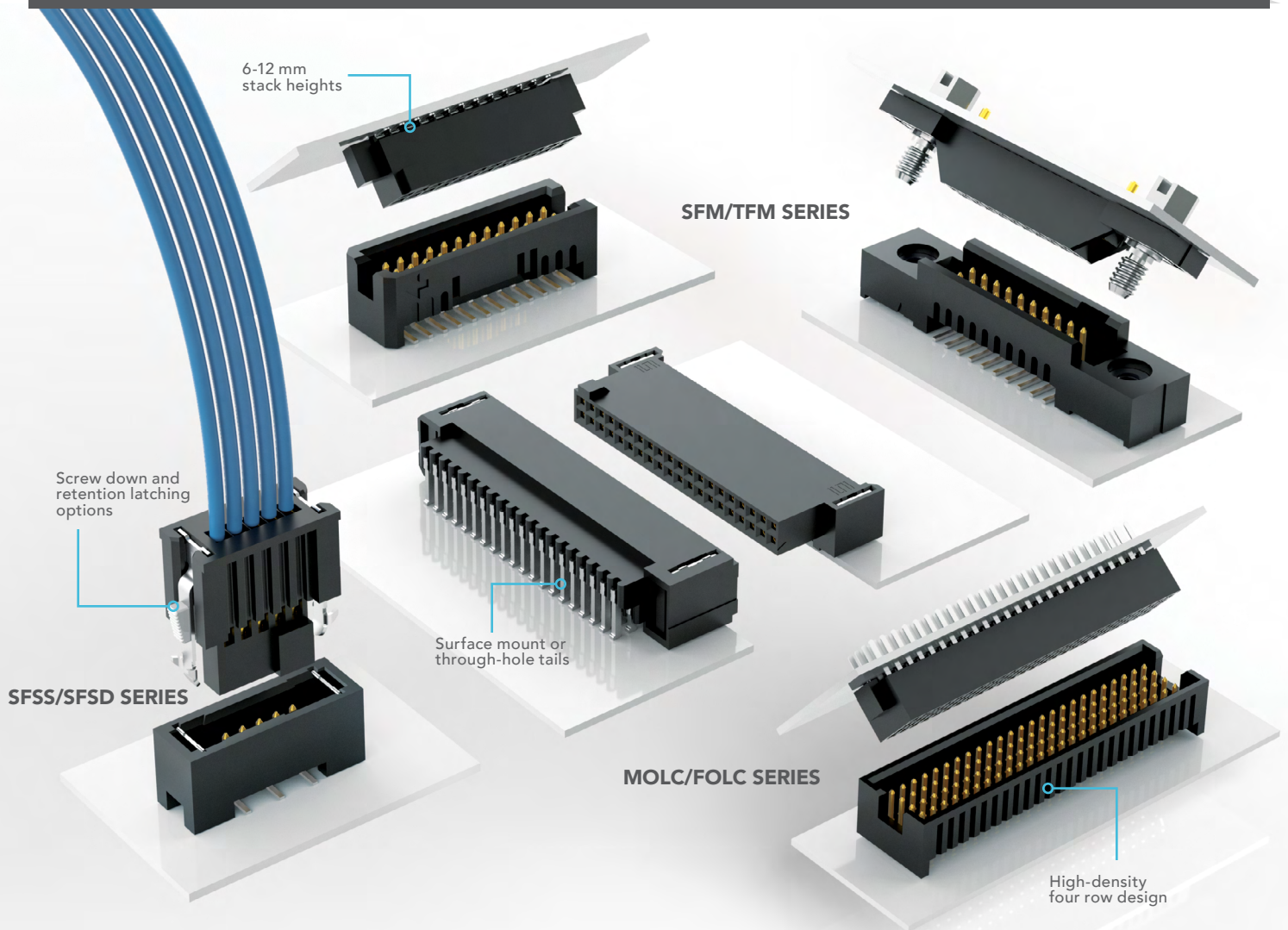
R MP

TIGER EYE™ CONTACT SYSTEMS

TIGER EYE™
CONTACT



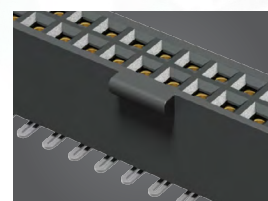
HIGH-RELIABILITY • MULTI-FINGER BeCu CONTACT • HIGH MATING CYCLES



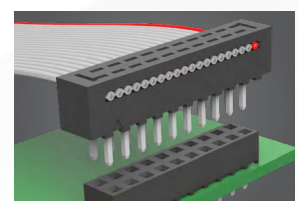
1.27 mm PITCH TIGER EYE™ SYSTEM

- Tiger Eye™ is Samtec's most rugged contact system rated to 1,000+ mating cycles
- Screw down, locking clip, friction latching and weld tab ruggedizing options
- Shrouded, polarized and keyed
- Discrete wire assemblies available in single or double row, 30 and 28 AWG PVC or Teflon® wire

Dupont™ Teflon® is a registered trademark of the E.I. du Pont de Nemours and Company or its affiliates.



LOCKING FOR INCREASED UNMATING FORCE (SFML SERIES)



MATING IDC CABLE ASSEMBLIES (FFXD & FFXP SERIES)

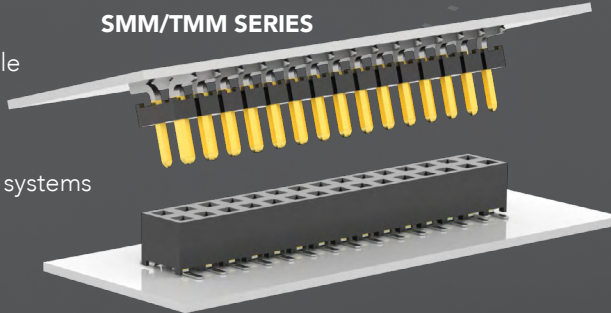


Samtec stamps over
1 BILLION Tiger Eye™
contacts per year.

2.00 mm PITCH TIGER EYE™ SYSTEM

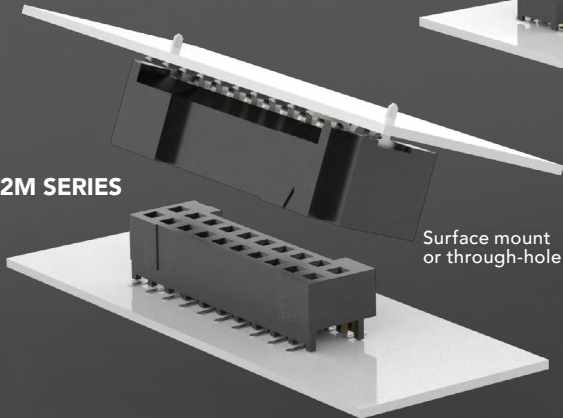
- Wide range of stack heights
- Right-angle mating headers available
- Optional screw downs, weld tabs and locking clips
- Mating discrete wire and IDC cable systems

SMM/TMM SERIES



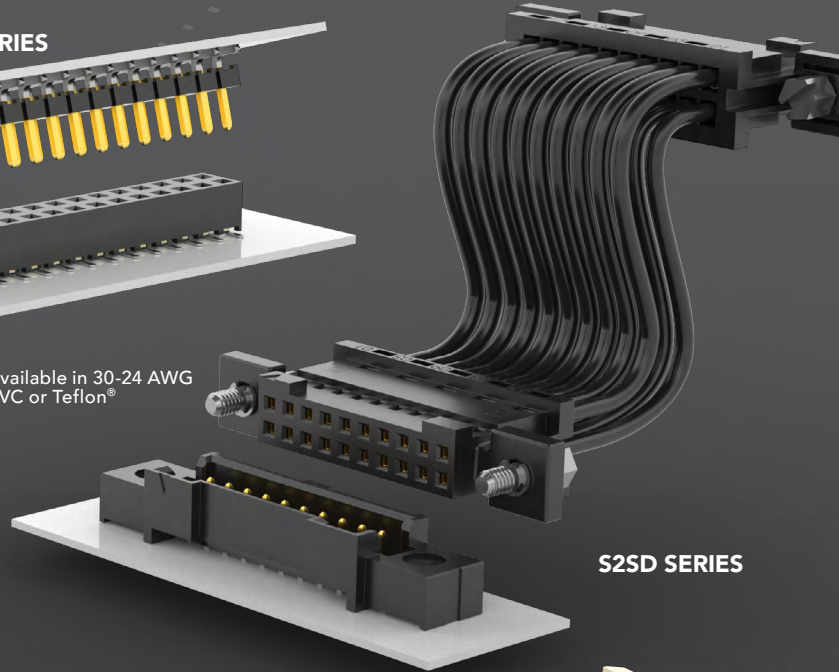
Available in 30-24 AWG
PVC or Teflon®

S2M/T2M SERIES



Surface mount
or through-hole

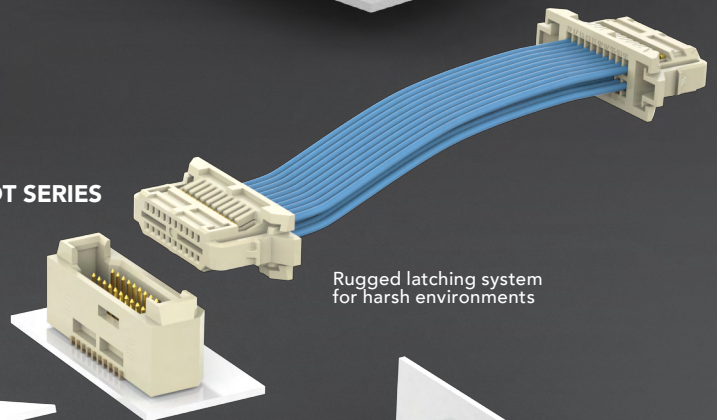
S2SD SERIES



0.80 mm PITCH TIGER EYE™ SYSTEM

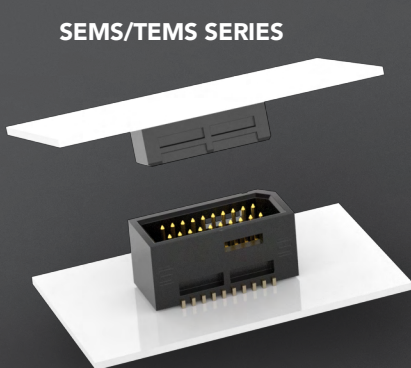
- Micro pitch and slim body for space-savings
- 6 mm, 7 mm and 10 mm stack heights
- Locking clip, alignment pins and weld tab ruggedizing features
- Discrete wire assembly with 32 AWG Teflon® wire

SESDT SERIES

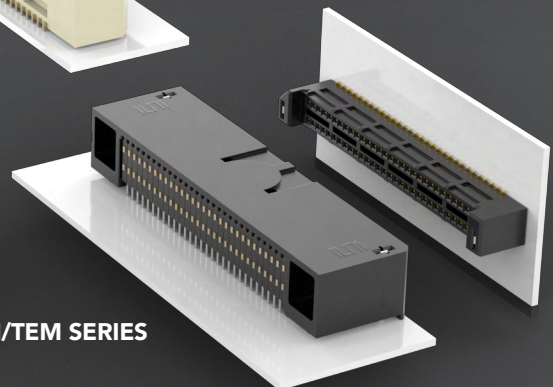
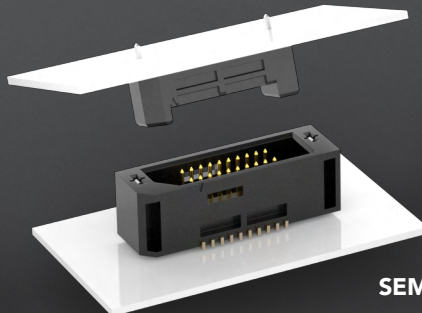


Rugged latching system
for harsh environments

SEMS/TEMS SERIES



SEM/TEM SERIES



Vertical and right-angle
mating headers

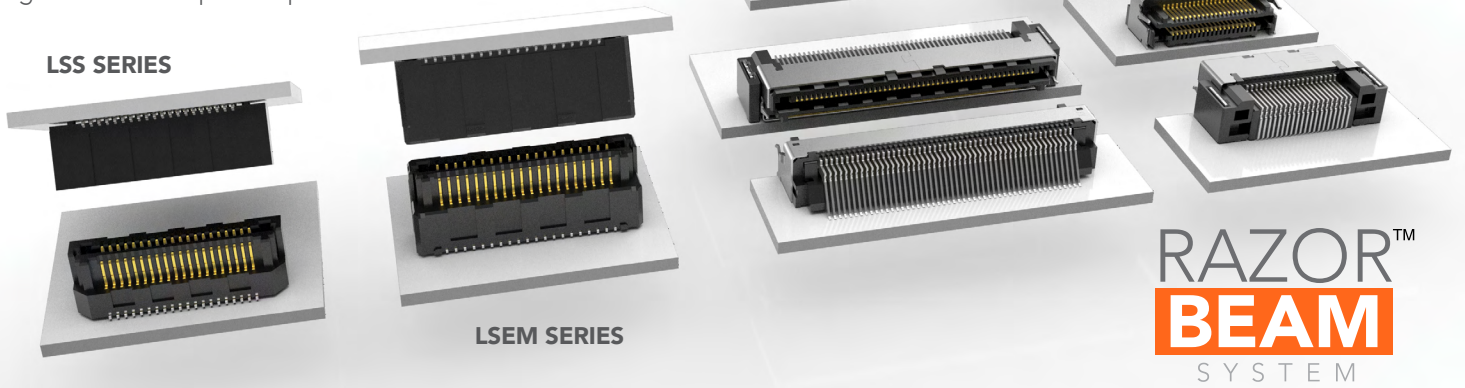
MICRO SYSTEMS

HIGH-DENSITY • HIGH-RETENTION CONTACTS • SLIM ROW-TO-ROW DESIGNS

HERMAPHRODITIC RAZOR BEAM™ INTERFACES

- High-retention, high-speed Razor Beam™ contacts
- 26 Gbps high-speed channel performance*
- 0.50 mm, 0.635 mm and 0.80 mm pitch
- EMI shielding available to limit signal degradation and optimize performance

5 - 12 mm stack height flexibility



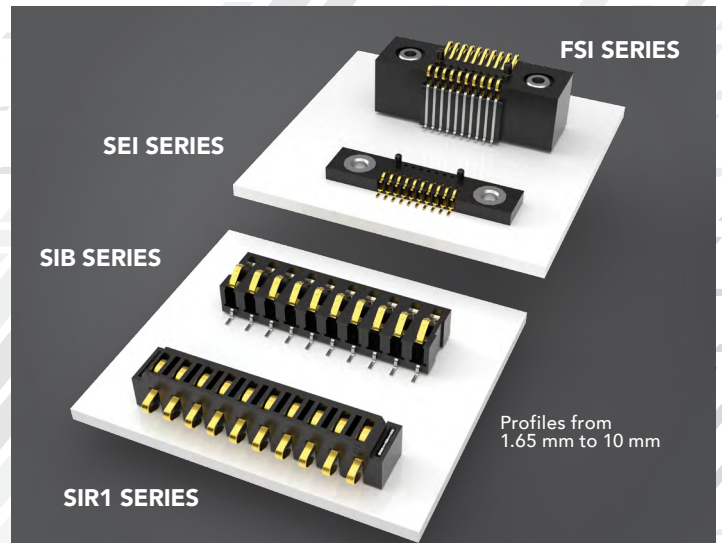
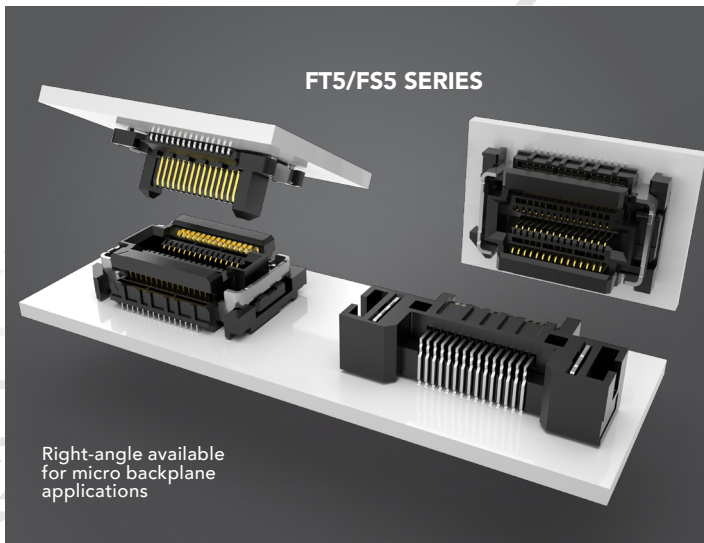
RAZOR BEAM™ SYSTEM

FLOATING CONNECTORS

- Provides 0.50 mm contact float in the X and Y axes to compensate for misalignment
- 5 mm and 7 mm stack heights
- Micro 0.50 mm pitch

ONE-PIECE INTERFACES

- Robust design and mechanical hold-downs for high-shock and vibration applications
- Optional rugged weld tabs and locking clips
- 1.00 mm, 1.27 mm and 2.54 mm pitch designs



* High-speed channel performance figure based on Samtec reference channel. For full SI Performance data visit samtec.com or contact sig@samtec.com

SI R MP



Lead times for custom products are often the same as for Samtec's standard products.

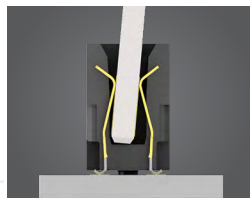
HIGH-SPEED EDGE CARD

16 TO 40 Gbps • CHOICE OF PITCH • EDGE RATE® CONTACTS

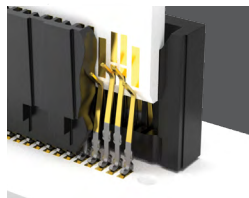
0.80 mm & 1.00 mm PITCH SYSTEMS

- High-speed Edge Rate® contact system
- Vertical, right-angle and edge mount
- Power/signal combo to 60 A per power bank
- Pass-through application

HSEC8 SERIES



MISALIGNMENT MITIGATION (HSEC1-DV SERIES)



40 Gbps WITH DIFFERENTIAL PAIR (HSEC8-DP SERIES)



40 Gbps

Rugged locking, latching and weld tab options

HSEC8-PV SERIES

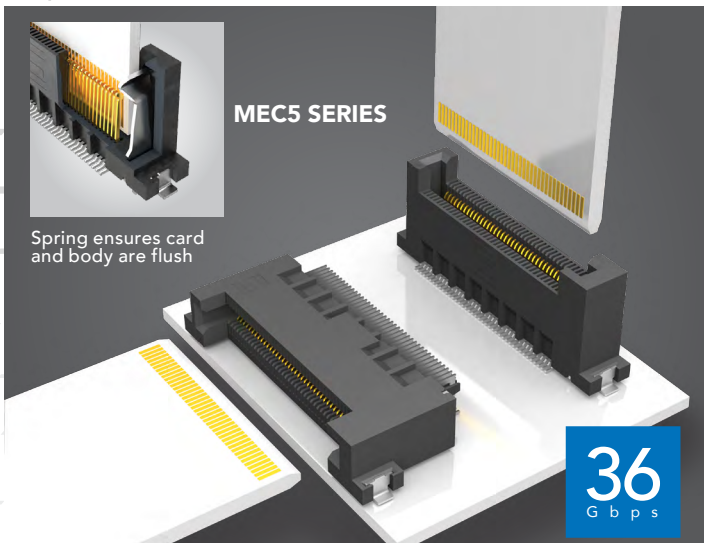
HSEC1-DV SERIES

HIGH-DENSITY EDGE CARD SYSTEM

- Justification beam enables use of standard PCB tolerance
- 0.50 mm ultra-fine pitch with up to 200 total I/Os
- PCIe® Gen 4 compliant

MICRO EDGE CARD SYSTEMS

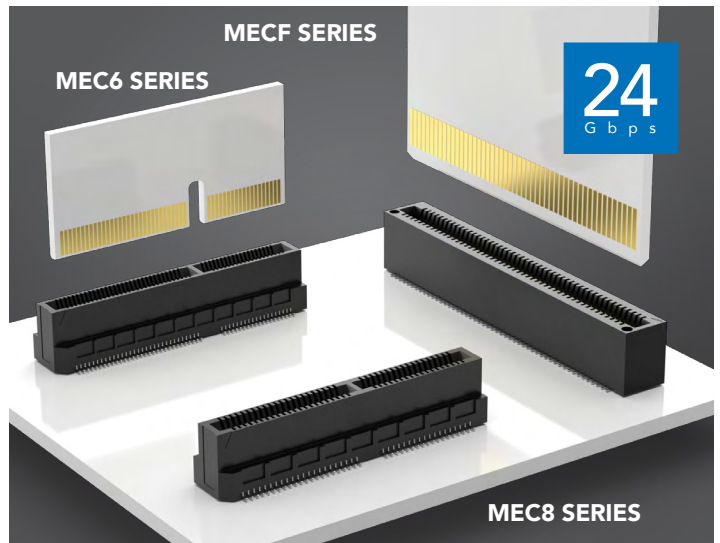
- 0.635 mm, 0.80 mm, 1.00 mm, 1.27 mm and 2.00 mm pitch
- Optional rugged weld tabs, board locks and solder locks
- Solutions for 1.60 mm (0.62") and 2.36 mm (.093") thick cards



MEC5 SERIES

Spring ensures card and body are flush

36 Gbps



MECF SERIES

MEC6 SERIES

24 Gbps

MEC8 SERIES

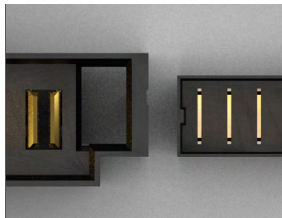
PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

POWER/SIGNAL SYSTEMS

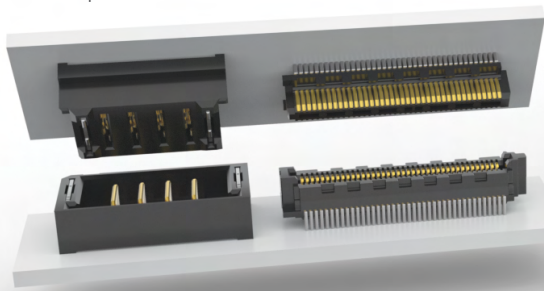
3 TO 15 A PER BLADE • MICRO PITCH • DESIGN FLEXIBILITY AND CONFIGURABILITY

MICRO POWER SYSTEMS

- 5 mm to 20 mm stack heights
- Use with Samtec's high-speed connector systems
- Design flexibility as a two-piece system for power/signal applications
- 2 to 5 power blades on a 2.00 mm pitch

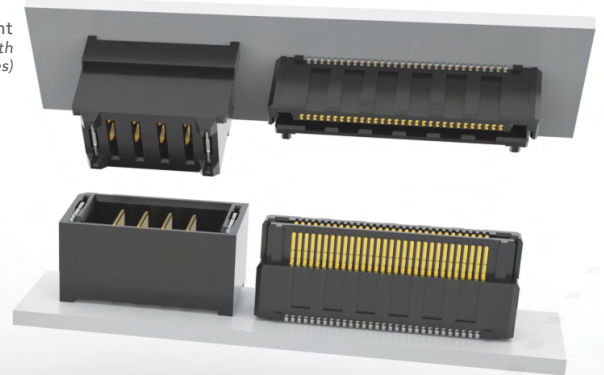


2.00 mm PITCH VS.
3.81 mm PITCH (UPX SERIES)



10 mm stack height
Micro Power shown with
Razor Beam™ (LSHM Series)

UMPT/UMPS SERIES

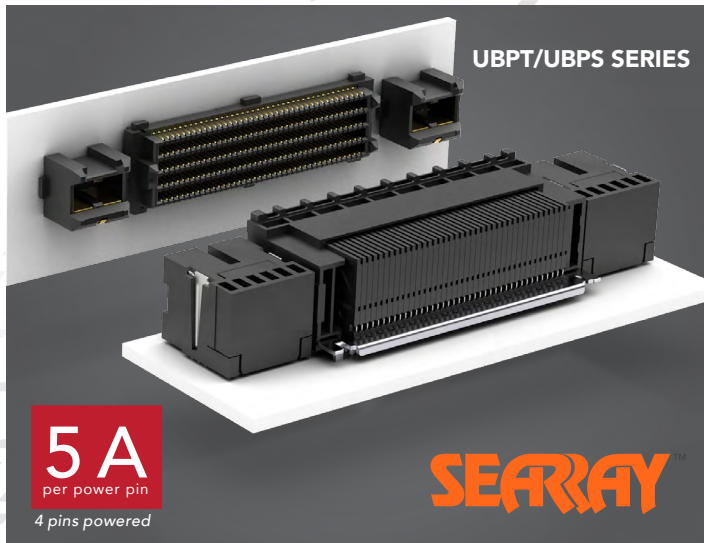


5 mm stack height
Micro Power shown with
Razor Beam™ LP (ST4/SS4 Series)

15 A
per power pin
4 pins powered

SEARAY™ HIGH-DENSITY POWER/SIGNAL COMBO

- Vertical and right-angle power modules for use with SEARAY™ and SEARAY™ 0.80 mm
- 0.80 mm and 1.27 mm pitch open-pin-field arrays
- Edge Rate® contact system less prone to damage when "zippered" to unmate



UBPT/UBPS SERIES

5 A
per power pin
4 pins powered

SEARAY™

Q2™ POWER/SIGNAL COMBO

- Increased insertion depth for rugged applications
- 0.635 mm pitch with integral power/ground plane
- Shielding, power pins, retention pins and RF options
- Eight total power pins at 4 A per pin (4 pins powered)



QMSS/QFSS SERIES

15 A
ground plane

Q2™



Custom designs make up almost 28% of Samtec's business. See page 15 for more information.

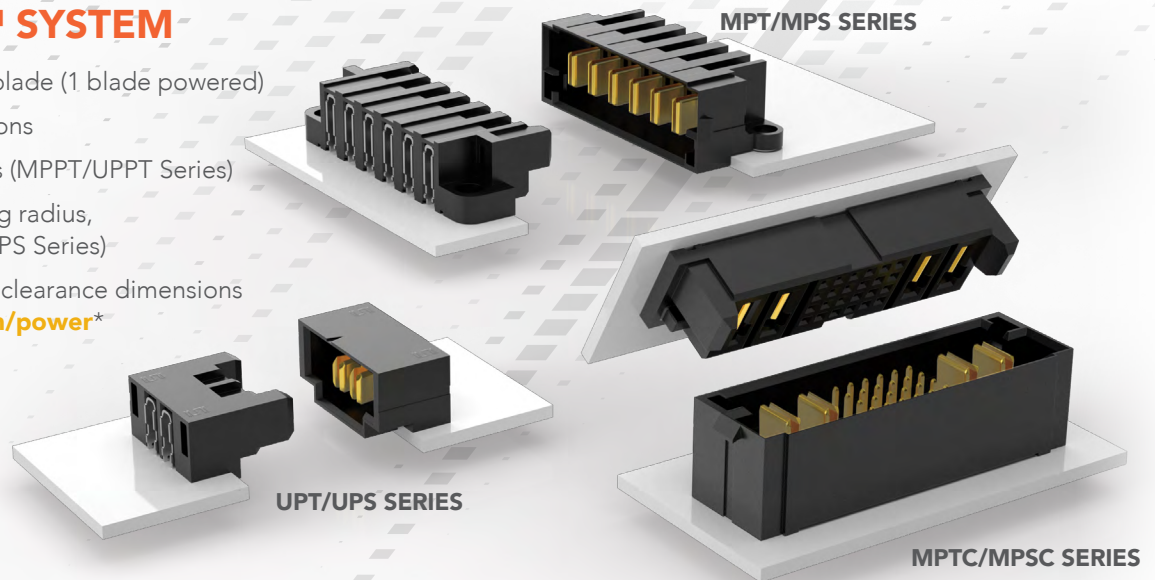


HIGH POWER SYSTEMS

20 TO 60 A PER BLADE • CHOICE OF PITCH • LOW PROFILE DESIGNS

POWERSTRIP™ SYSTEM

- 23.5 A/blade to 58.7 A/blade (1 blade powered)
- Power/signal combinations
- Hermaphroditic headers (MPPT/UPPT Series)
- “Hinging” for 90° mating radius, blind mating (FMPT/FMPS Series)
- Standard creepage and clearance dimensions available at samtec.com/power*

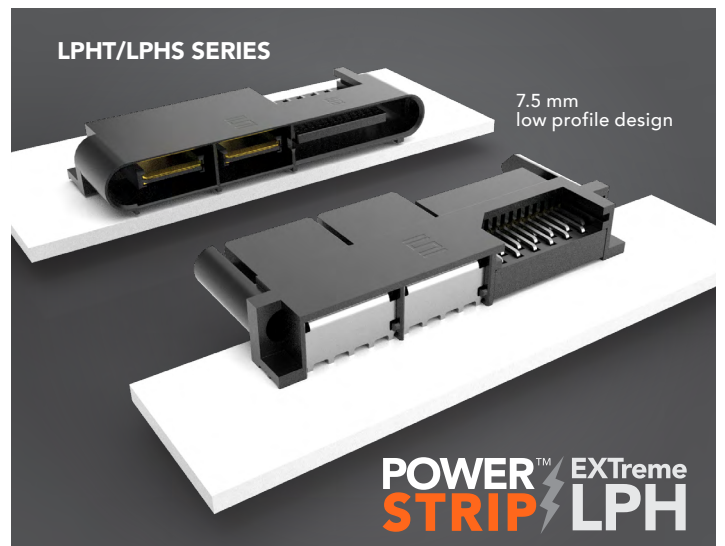
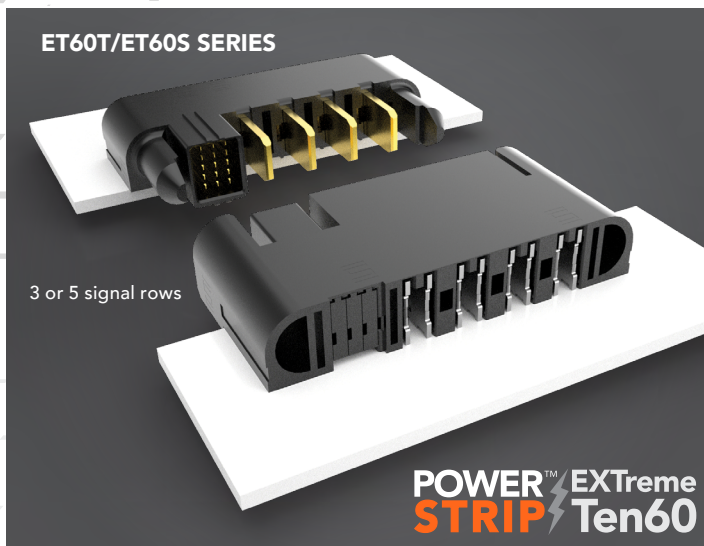


EXTREME TEN60POWER™

- Up to 60 A/blade (2 blades powered)
- High-density signals available in the same form factor
- AC power, AC-DC combos and split power options
- Standard creepage and clearance dimensions available at samtec.com/power*

EXTREME LPHPOWER™

- Up to 30 A/blade (4 blades powered)
- High-density, double stacked power blades
- 16, 20, 24 and 32 signal options
- Standard creepage and clearance dimensions available at samtec.com/power*



* For flexible design solutions to fit specific applications, contact Samtec.

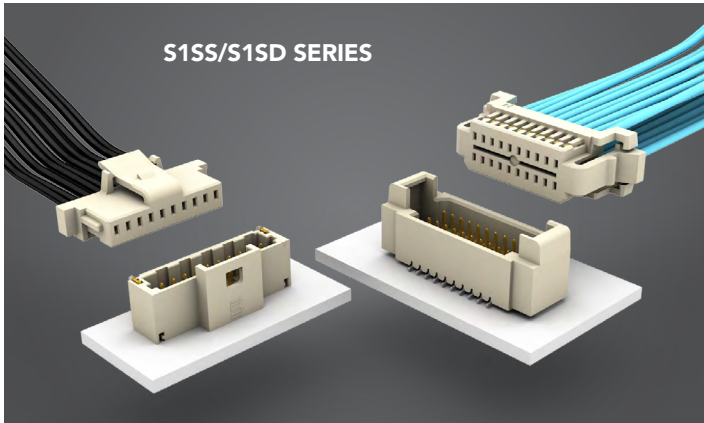


MICRO DISCRETE WIRE

CHOICE OF PITCH • 3 TO 35 A PER CONTACT • RUGGED LATCHING

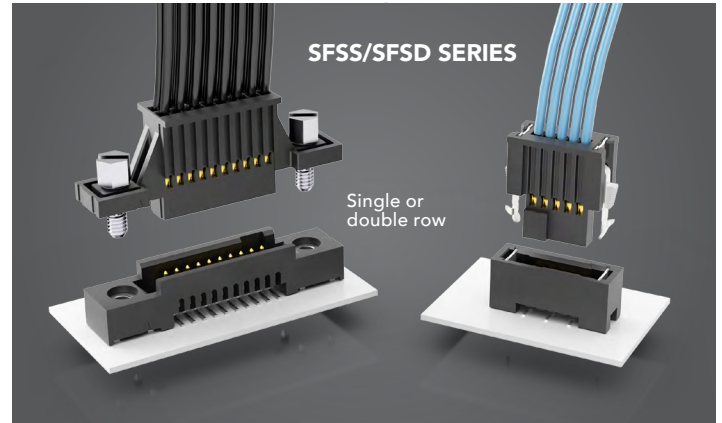
1.00 mm PITCH SYSTEM

- 3.3 A/contact*
- 2 to 20 total pins, single or double row
- Low profile down to 3.2 mm
- Available with or without retention latch



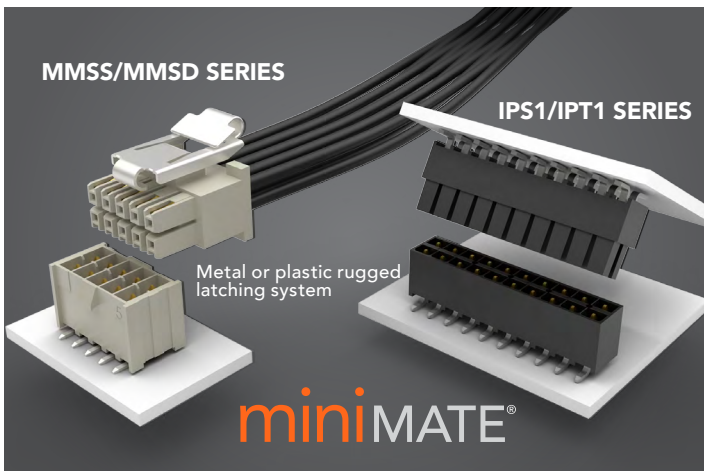
1.27 mm PITCH TIGER EYE™ SYSTEM

- 2.9 A/contact*
- High-reliability, multi-finger BeCu Tiger Eye™ contacts
- Rugged screw down and retention latch options



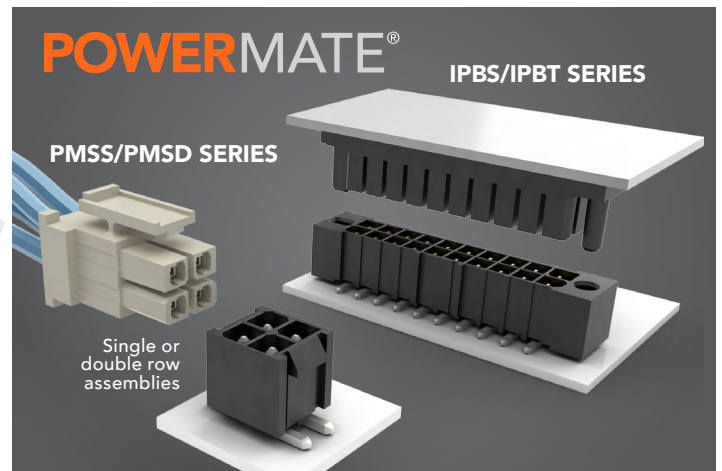
MINI MATE® SYSTEM

- 5.4 A/contact*
- .100" (2.54 mm) pitch with individually shrouded contacts
- Panel mount cable assembly accommodates panel thickness of 0.84 mm to 2.28 mm



POWER MATE® SYSTEM

- 10.3 A/contact*
- .165" (4.19 mm) pitch with individually shrouded contacts
- Standard creepage and clearance dimensions available at samtec.com/power**



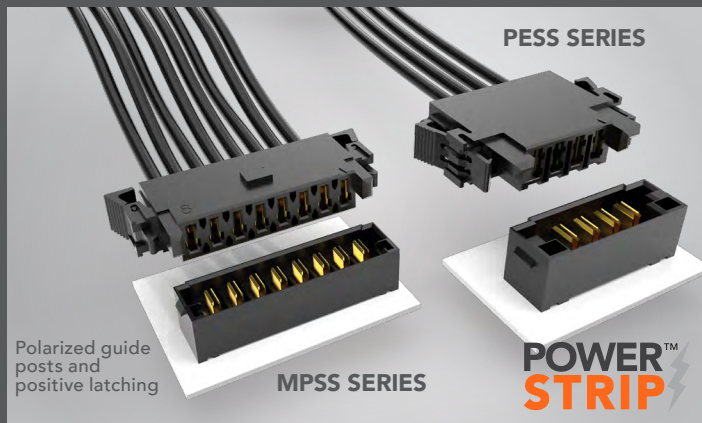
* 1 contact/blade powered per row ** For flexible design solutions to fit specific applications, contact Samtec.



36% of Samtec's discrete wire sales are modified and custom products. See page 15 for more information.

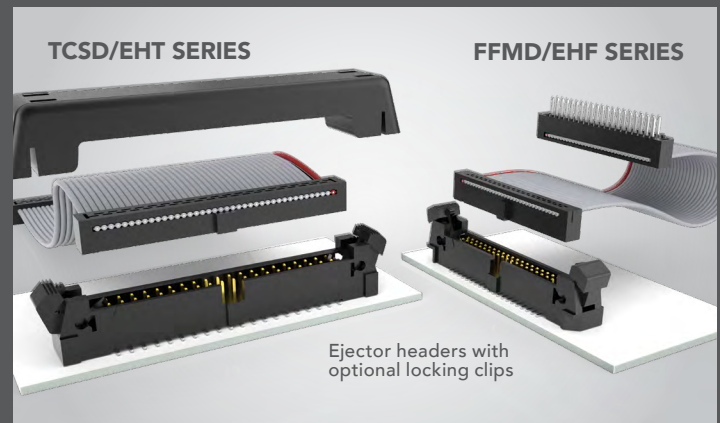
POWERSTRIP™ SYSTEM

- 5.00 mm pitch for performance to 23.2 A/blade* and 6.35 mm pitch for 34.5 A/blade* performance
- Power/signal combination
- Standard creepage and clearance dimensions available at samtec.com/power**



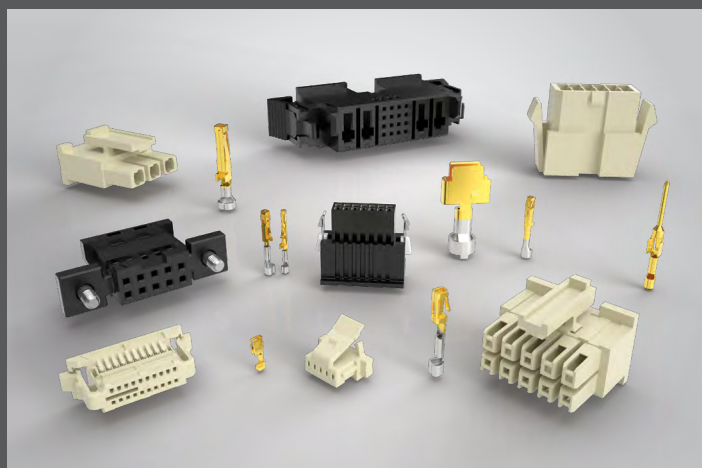
MICRO RUGGED IDC CABLE SYSTEMS

- 1.27 mm and 2.00 mm pitch systems with low 5.08 mm profile
- High-reliability Tiger Eye™ contacts
- Variety of options including rugged strain relief, polarization and daisy chains



DISCRETE WIRE COMPONENTS

- A broad selection of housings and contacts for build-it-yourself design and application flexibility
- Rugged screw downs, plastic and metal latches
- 32 to 10 AWG wire



DISCRETE WIRE TOOLING

- Hand tools and quick-change semi-automatic crimp applicators available
- Wide variety of additional application specific hardware and field service capabilities
- Visit samtec.com/discretewire or samtec.com/tooling



* 1 contact/blade powered per row ** For flexible design solutions to fit specific applications, contact Samtec.



ACCLIMATE™ SEALED I/O

IP67 & IP68 • BAYONET/PUSH-PULL CIRCULARS • SPACE-SAVING RECTANGULARS

FLEXIBLE SEALED CIRCULAR SYSTEMS

- Metal or plastic, 12 mm, 16 mm & 22 mm shells
- Flexible pin configuration, gender and panel interface termination
- Bayonet-style latching systems meet IP68 requirements
- Cost-effective crimp version available
- Mini push-pull latching system meets IP67 requirements for dust and waterproof sealing

ACP/ACR SERIES

16 mm size metal shell

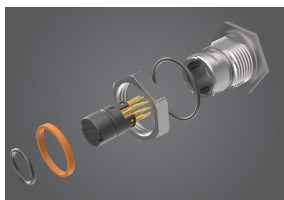


CCP/CCR SERIES

Crimp 12 mm shell

MCP/MCR SERIES

Mini push-pull system



KITTED COMPONENTS FOR
EFFICIENT FIELD ASSEMBLY

ACCLIMATE™

ETHERNET AND USB SEALED SYSTEMS

- IP68 threaded circulars with rugged overmold design
- Space-saving rectangulars with positive latching for quick connect/disconnect
- IP67 sealed USB Type C port seals to panel without costly metal screws or dust caps

RCE/RPBE SERIES

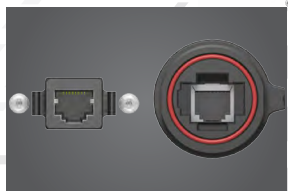
SCRUS/SCPU SERIES

SSU-C SERIES

Meets USB 2.0 and
base 3.1 standards

USB or Ethernet (meets
CAT3, CAT5 & CAT5e)

10 or 17 mm shell
size for Ethernet,
Mini USB and USB

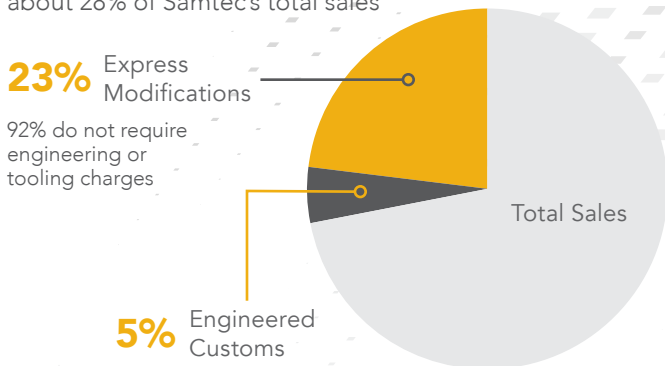


25-45% PANEL AREA SAVINGS

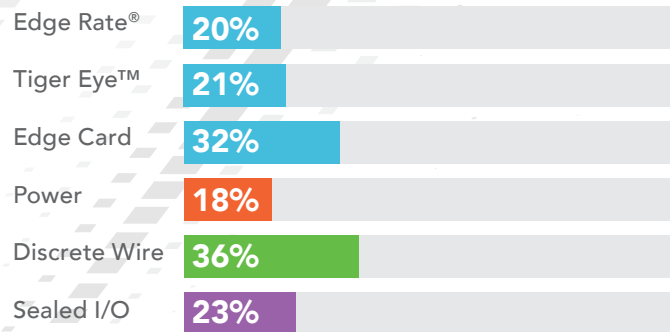
MODIFIED & CUSTOM SOLUTIONS

WILLINGNESS, SUPPORT & EXPERTISE

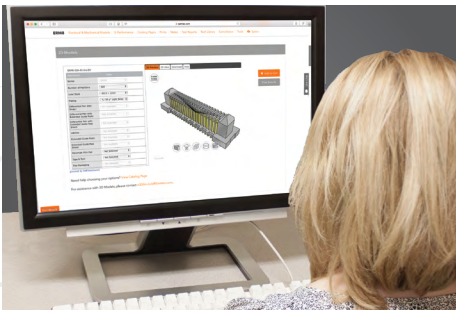
Customs and Modifications make up about 28% of Samtec's total sales



A substantial percentage of each Micro Rugged product segment is custom



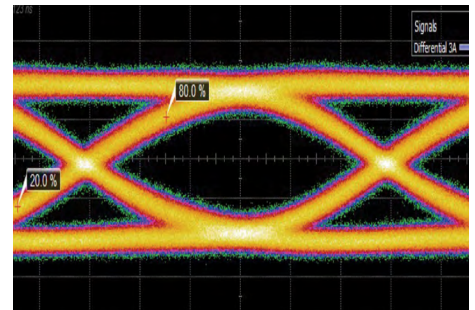
INDUSTRY LEADING CUSTOMER SERVICE



FLEXIBLE IN-HOUSE MANUFACTURING

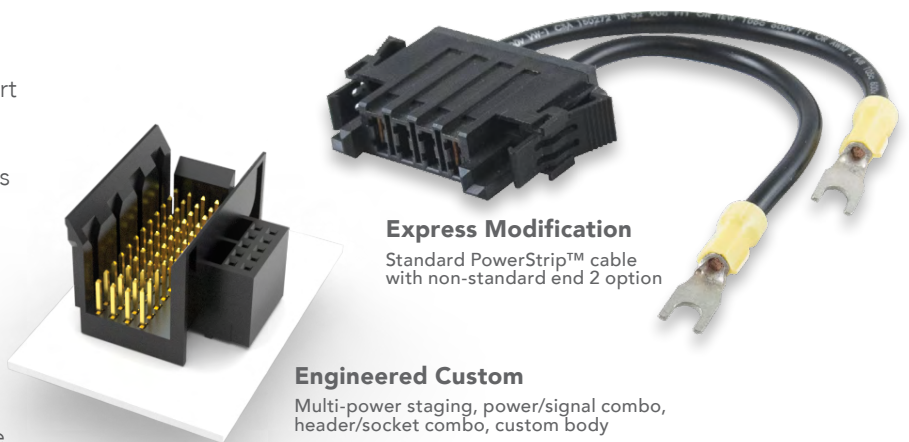


SIGNAL INTEGRITY EXPERTISE



FLEXIBLE CAPABILITIES

- Full engineering, design and prototype support
- Design, simulation and processing assistance
- Quotes and samples turned around in 24 hours
- Flexible, quick-turn manufacturing
- Dedicated Application Specific Product engineers and technicians
- Modified or custom options for board level connectors and cable assemblies including: contacts, bodies, stamping, plating, wiring, molding, ruggedizing features and much more



Contact the Application Specific Products Group at asp@samtec.com for express modifications or customasp@samtec.com for engineered customs.

SOLUTIONATOR®

QUICKLY BUILD MATED SETS ONLINE

- Wide variety of search parameters and filters: creepage and clearance, pitch, stack height, etc.
- Easily sort results to find the right mated set
- Live chat with engineers for custom options
- Immediately download models and open Specs Kit

The screenshot displays the Solutionator website interface. At the top, the logo reads "Solutionator DESIGN IN A MINUTE". Below the logo is a search bar with the text "Search by Keyword, Series, or Part #, or Use the Parametric Filters Below".

The "Search Options (Choose As Many As Apply)" section includes several filters:

- Pitch:** A dropdown menu set to "0.80 mm (.0315)".
- Stack Height:** A range filter with a checked box, a "min." input set to "0", and a "max." input set to "12". Units are "mm" and "in".
- Creepage:** A range filter with a "min." input set to "0" and units "mm" and "in".
- Clearance:** A range filter with a "min." input set to "0" and units "mm" and "in".
- Contact System:** A dropdown menu set to "Edge Rate".
- Mating Orientation:** A dropdown menu set to "Coplanar".

Below the search options, there are sections for "Active Filters" and "87 Results". The "Active Filters" section shows: "Pitch: 0.80 mm (.0315)", "Stack Height: Range of values (1630)", "Positions: Range of values (1350)", and "Contact System: Edge Rate (87)".

The "87 Results" section contains a table with the following columns: Part Number, Mating Part Number, Pitch, Mated Stack Height (mm), Positions, Board Termination, Mating Orientation, Rugged Rating, Signal Integrity Rating, and Creepage (mm).

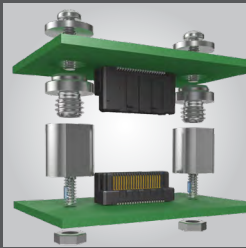
Part Number	Mating Part Number	Pitch	Mated Stack Height (mm)	Positions	Board Termination	Mating Orientation	Rugged Rating	Signal Integrity Rating	Creepage (mm)
ERM8-030-02.0-L-DV-TR	ERF8-030-07.0-S-DV-TR	0.80 mm (.0315")	9	60	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-070-02.0-L-DV-TR	ERF8-070-07.0-S-DV-TR	0.80 mm (.0315")	9	140	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-050-05.0-L-DV-K-TR	ERF8-050-05.0-L-DV-K-TR	0.80 mm (.0315")	10	100	Surface Mount	Parallel	3 - Edge Rate	16 GHZ	NA
ERM8-070-02.0-L-DV-TR	ERF8-070-05.0-L-DV-TR	0.80 mm (.0315")	7	140	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
QRM8-052-05.0-L-D-A	QRF8-052-07.0-L-D-A	0.80 mm (.0315")	12	104	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-020-05.0-L-DV-TR	ERF8-020-07.0-L-DV-TR	0.80 mm (.0315")	12	40	Surface Mount	Parallel	3 - Edge Rate	NA	NA
SEAM8-10-S02.0-S-10-2-K	SEAF8-10-05.0-S-10-2-K	0.80 mm (.0315")	7	100	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-025-02.0-L-DV-TR	ERF8-025-05.0-S-DV-TR	0.80 mm (.0315")	7	50	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-010-02.0-L-DV-TR	ERF8-010-05.0-S-DV-TR	0.80 mm (.0315")	7	20	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-070-05.0-L-DV-TR	ERF8-070-05.0-L-DV-TR	0.80 mm (.0315")	10	140	Surface Mount	Parallel	3 - Edge Rate	16 GHZ	NA
ERM8-025-02.0-L-DV-K-TR	ERF8-025-05.0-L-DV-K-TR	0.80 mm (.0315")	7	50	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA

At the bottom of the interface, there is a "Feedback" button and a "Live Chat" button.

www.samtec.com/solutionator

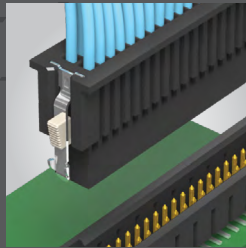
RUGGED FEATURES

RUGGEDIZING OPTIONS



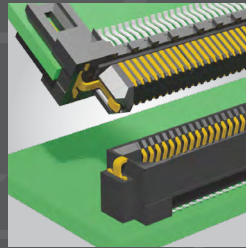
JACK SCREWS

Ideal for high normal force, zipping and other rugged applications



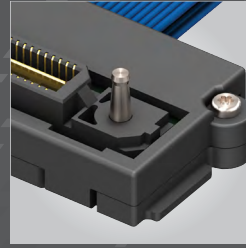
POSITIVE LATCHING

Manually activated latches increase unmating force by up to 200%



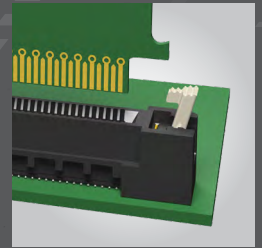
FRICTION LOCKS

Metal or plastic friction locks increase retention/withdrawal force



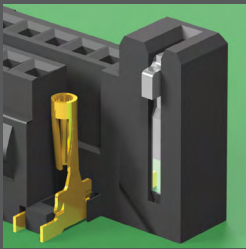
RETENTION PINS

Increase unmating force by up to 50%



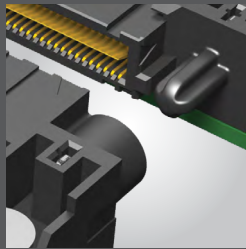
BOARD LOCKS

Boards are mechanically locked together



WELD TABS

Significantly increase shear resistance of connector to PCB



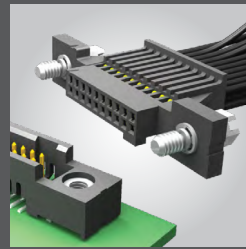
GUIDE POSTS

Easy and secure mating



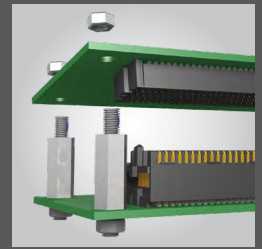
SHIELDING

360° shielding reduces EMI



SCREW DOWNS

Secure mechanical attachment to the board



BOARD STANDOFFS

Precision machined standoffs for 5 mm to 25 mm board spacing

CONTACT SYSTEMS



TIGER EYE™

High-reliability
High Mating Cycles
Multi-finger Contact



TIGER CLAW™

Dual Wipe Contact
Pass-through Applications
Ultra-low Profile



BLADE & BEAM

Mating/Alignment "Friendly"
Cost-effective



TIGER BEAM™

Best Cost
Reliable Performance
Post & Beam Contact



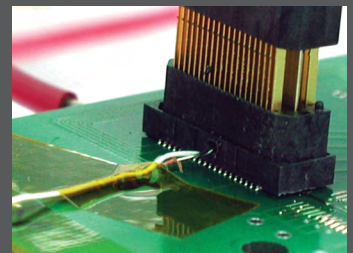
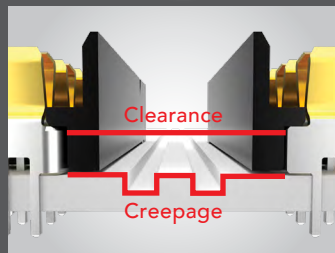
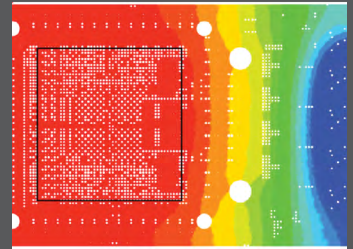
EDGE RATE®

Designed for Signal Integrity
Superior Impedance Control
Reduced Broadside Coupling

POWER INTEGRITY & E.L.P.TM

POWER INTEGRITY SERVICES

- Standard power test data, including current carrying capacity, working voltage, voltage drop and resistance, creepage and clearance, is available for select power systems
- Current Cycling Test Data, which demonstrates connector performance in realistic and common applications, is available for select series
- Power Integrity Guidelines are based on test data and proven design parameters, and are designed to help in connector selection and PCB design maximization
- Power Integrity Certified products undergo testing and additional requirements unique to Samtec. To be certified, products must pass Current Cycling Test EIA 365-55, have current carrying capacity, resistance and amps vs. number of contacts data available and Power Integrity Guidelines developed
- Visit samtec.com/powerintegrity for more information



EXTENDED LIFE PRODUCTTM

E.L.P.TM products are tested to rigorous standards, which evaluate contact resistance in simulated storage and field conditions.



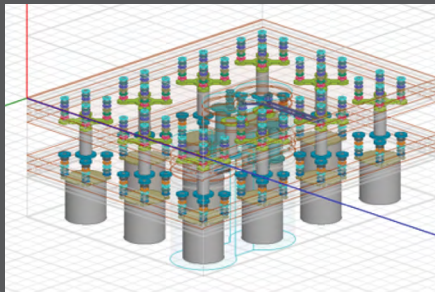
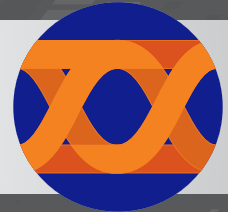
- 10 year Mixed Flowing Gas (MFG)
- High Mating Cycles (250 to 2,500)
- Certain plating and/or contact options will apply
- For complete details on Samtec's E.L.P.TM program, a list of qualifying products and test results, please visit samtec.com/ELP or email the Customer Engineering Support Group at CES@samtec.com

PITCH	TYPE	CONTACT	SERIES*
0.50 mm	Q Series [®] Strip	Blade & Beam	QSH/QTH
	Basic Strip	Blade & Beam	BSH/BTH
0.635 mm	Q Series [®] Strip	Blade & Beam	QSS/QTS
	Basic Strip	Blade & Beam	BSS/BTS
0.80 mm	Edge Rate [®] Strip	Edge Rate [®]	ERF8/ERM8
	Edge Card	Edge Rate [®]	HSEC8
	Q Rate [®] Strip	Edge Rate [®]	QRM8/QRF8
	Q Series [®] Strip	Blade & Beam	QSE/QTE
	Basic Strip	Blade & Beam	BSE/BTE
1.00 mm	Strip	Tiger Eye [™]	SEM/TEM
	SEARAY [™] Array	Edge Rate [®]	SEAF/SEAM
1.27 mm	Strip	Tiger Eye [™]	SFM/TFM
	Strip	Tiger Claw [™]	CLP/FTSH
	Strip	Tiger Beam [™]	FLE/FTSH
2.00 mm	Strip	Tiger Eye [™]	SMM/TMM
	Strip	Tiger Claw [™]	CLT/TMMH
2.54 mm	Strip	Tiger Claw [™]	SSM/TSM
	Strip	Tiger Claw [™]	BCS/TSW

* Tested socket/terminal combination shown. Other mating headers also available. Contact Samtec if header design you need is not shown.

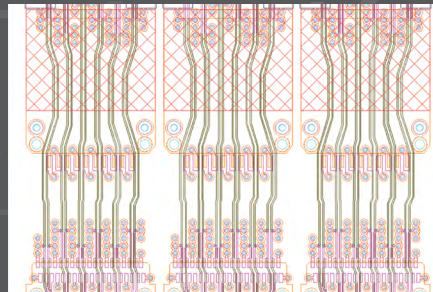
FULL SYSTEM SIGNAL INTEGRITY

Teraspeed® and Signal Integrity Group Engineers Help Optimize and Validate Your High-Performance System. Services are available at any level you require: from early stages of the design process including package design, materials selection and PCB routing, through in-depth analysis, modeling and simulation, with measurement validation services available to 67 GHz.



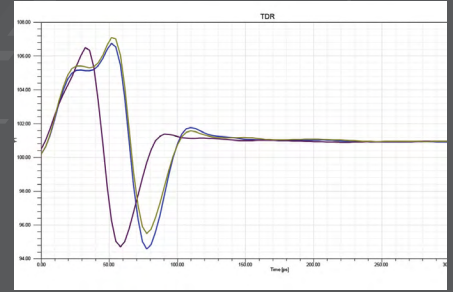
PACKAGE DESIGN & MATERIALS

- Bumpout / Ballout Optimization
- Layout & Routing
- Ballout Transition Structures
- Material Recommendations



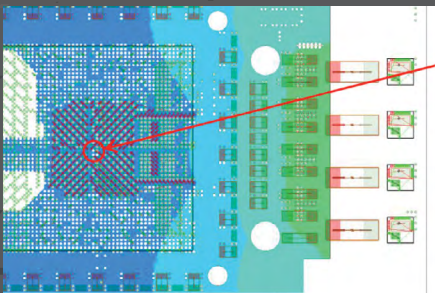
MODELING

- High Bandwidth Full-Wave
- Custom & Commercial Software



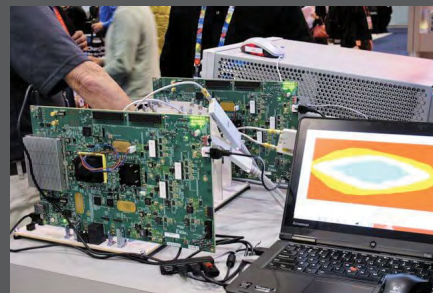
SIMULATION

- Design Rules for Package & PCB Designs
- Validate Implementation and Signaling Requirements for Critical Channels
- Simulations via High-Performance Computing



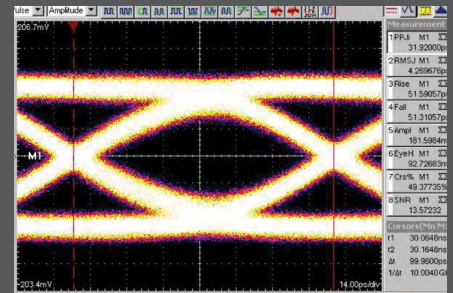
ANALYSIS

- Package, PCB and System-Level Power Integrity
- Package, PCB and System-Level Signal Integrity



TESTING

- Post Design Simulation & Measurements
- Measurement of Test Structures for Signal Integrity / Power Integrity Optimization
- Material Characterization



VALIDATION

- Validation Platform Engineering
- Connectors, Packages & Devices
- Characterization at Frequencies to 67 GHz



samtec
SUDDEN SERVICE®

UNITED STATES • NORTHERN CALIFORNIA • SOUTHERN CALIFORNIA • SOUTH AMERICA • UNITED KINGDOM • GERMANY • FRANCE • ITALY • NORDIC/BALTIC
BENELUX • ISRAEL • INDIA • AUSTRALIA / NEW ZEALAND • SINGAPORE • JAPAN • SHANGHAI • SHENZHEN • TAIWAN • HONG KONG • KOREA

FEBRUARY 2017